

## **Thyristor**

1600 V

57 A

 $V_{\mathsf{T}}$ 1.2 V

### Single Thyristor

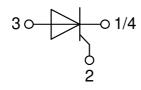
Part number

#### MCO50-16io1



Backside: isolated





#### Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability

#### **Applications:**

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter AC power control
- Lighting and temperature control

Package: SOT-227B (minibloc)

- Isolation Voltage: 3000 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Base plate: Copper
- internally DCB isolated
- Advanced power cycling

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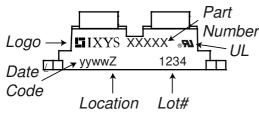
Thyristo		0			Ratings	1	١,,,
Symbol	Definition	Conditions	T 0500	min.	typ.	max.	Un
V <sub>RSM/DSM</sub>	max. non-repetitive reverse/forwa		$T_{VJ} = 25^{\circ}C$			1700	1
V <sub>RRM/DRM</sub>	max. repetitive reverse/forward bloom		$T_{VJ} = 25^{\circ}C$			1600	 
I <sub>R/D</sub>	reverse current, drain current	$V_{R/D} = 1600 \text{ V}$	$T_{VJ} = 25^{\circ}C$			50	μ
		$V_{R/D} = 1600 \text{ V}$	$T_{VJ} = 125^{\circ}C$			3	m
V <sub>T</sub>	forward voltage drop	$I_T = 50 \text{ A}$	$T_{VJ} = 25^{\circ}C$			1.27	,
		I <sub>T</sub> = 100 A				1.53	<u> </u>
		$I_{T} = 50 \text{ A}$	$T_{VJ} = 125$ °C			1.20	 
		$I_T = 100 A$				1.50	,
I <sub>TAV</sub>	average forward current	$T_C = 80^{\circ}C$	$T_{VJ} = 150$ °C			57	
I <sub>T(RMS)</sub>	RMS forward current	180° sine				90	
V <sub>T0</sub>	threshold voltage		T <sub>vJ</sub> = 150°C			0.88	ļ ,
r <sub>T</sub>	slope resistance } for power lo	ess calculation only				6	m۵
R <sub>thJC</sub>	thermal resistance junction to cas	e				0.72	K/V
R <sub>thCH</sub>	thermal resistance case to heatsin	nk			0.2		K/V
P <sub>tot</sub>	total power dissipation		T <sub>C</sub> = 25°C			170	٧
I <sub>TSM</sub>	max. forward surge current	t = 10 ms; (50 Hz), sine	$T_{VI} = 45^{\circ}C$			740	
- 15W	5	t = 8.3  ms; (60 Hz), sine	$V_R = 0 V$			800	,
		t = 10  ms; (50  Hz),  sine	T <sub>v.i</sub> = 150°C			630	
		t = 8.3  ms; (60 Hz), sine	$V_R = 0 V$			680	
l²t	value for fusing	t = 10 ms; (50 Hz), sine	$T_{VJ} = 45^{\circ}C$			2.74	1
	value for rushing	t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			2.66	kA <sup>2</sup>
		t = 0.5  ms, (60 Hz), sine t = 10  ms; (50 Hz), sine	$V_{R} = 0 V$ $T_{VJ} = 150 ^{\circ}C$			1.99	1
		. , , , ,					į.
_	iunation consoltance	t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$		20	1.93	
C,	junction capacitance	V <sub>R</sub> = 400 V f = 1 MHz	$T_{VJ} = 25^{\circ}C$		32	10	p
$P_{GM}$	max. gate power dissipation	$t_P = 30 \mu s$	$T_{c} = 150^{\circ}C$			10	۷
_		$t_{P} = 300 \mu s$				1	۷
P <sub>GAV</sub>	average gate power dissipation					0.5	٧
(di/dt) <sub>cr</sub>	critical rate of rise of current	$T_{VJ} = 150 ^{\circ}\text{C}; f = 50 \text{Hz}$ re	•			100	A/μ
		$t_P = 200 \mu s; di_G/dt = 0.3 A/\mu s; -$					!
		$I_G = 0.3 A; V = \frac{2}{3} V_{DRM}$ no	on-repet., $I_T = 50 \text{ A}$			500	A/µ
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150$ °C			1000	V/µ
		R <sub>GK</sub> = ∞; method 1 (linear volta	ge rise)				! !
V <sub>GT</sub>	gate trigger voltage	V <sub>D</sub> = 6 V	$T_{VJ} = 25^{\circ}C$			1.4	١
			$T_{VJ} = -40$ °C			1.6	١
<b>I</b> <sub>GT</sub>	gate trigger current	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$			80	m/
			$T_{VJ} = -40$ °C			200	m/
V <sub>GD</sub>	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DBM}$	T <sub>vJ</sub> = 150°C			0.2	١
I <sub>GD</sub>	gate non-trigger current	5 5				5	m/
I <sub>L</sub>	latching current	t <sub>p</sub> = 10 μs	T <sub>vJ</sub> = 25°C			450	m
	Ŭ	$I_{\rm g} = 0.3  \text{A};  \text{di}_{\rm g}/\text{dt} = 0.3  \text{A}/\mu \text{s}$					,
I <sub>H</sub>	holding current	$V_{D} = 6 \text{ V } R_{GK} = \infty$	$T_{VJ} = 25$ °C			100	m
	gate controlled delay time	$V_{D} = \frac{1}{2} V_{DRM}$	$T_{VJ} = 25 ^{\circ}\text{C}$			2	<del>i</del>
t <sub>gd</sub>	gate controlled delay tille	$I_{G} = 72 V_{DRM}$ $I_{G} = 0.3 A; di_{G}/dt = 0.3 A/\mu s$				۷	μ
	turn-off time		150		-		
t <sub>q</sub>		$V_R = 100 \text{ V}; I_T = 50 \text{A}; V = \frac{2}{3}$					μ



Package	Package SOT-227B (minibloc)			Ratings				
Symbol	Definition	Conditions			min.	typ.	max.	Unit
I <sub>RMS</sub>	RMS current	per terminal 10					150	Α
T <sub>VJ</sub>	virtual junction temperatur	re			-40		150	°C
T <sub>op</sub>	operation temperature				-40		125	°C
T <sub>stg</sub>	storage temperature				-40		150	°C
Weight						30		g
M <sub>D</sub>	mounting torque				1.1		1.5	Nm
$\mathbf{M}_{_{T}}$	terminal torque				1.1		1.5	Nm
d <sub>Spp/App</sub>	oroonaga diatanaa an aurt	face Latriking diatance through air	terminal to terminal	10.5	3.2			mm
$d_{Spb/Apb}$	creepage distance on sun	face   striking distance through air	terminal to backside	8.6	6.8			mm
V <sub>ISOL</sub>	isolation voltage	t = 1 second	$t = 1$ second $t = 1$ minute 50/60 Hz, RMS; lisoL $\leq 1$ mA		3000			٧
1002		t = 1 minute			2500			٧

<sup>1)</sup>  $I_{\text{hus}}$  is typically limited by the pin-to-chip resistance (1); or by the current capability of the chip (2). In case of (1) and a product with multiple pins for one chip-potential, the current capability can be increased by connecting the pins as one contact.



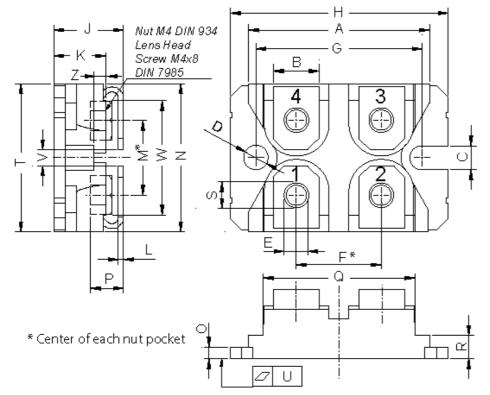


Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MCO50-16io1	MCO50-16io1	Tube	10	500598

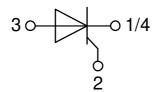
<b>Equivalent Circuits for Simulation</b>			* on die level	$T_{VJ} = 150$ °C
$I \rightarrow V_0$	)— <u>R</u> o	Thyristor		
V <sub>0 max</sub>	threshold voltage	0.88		V
R <sub>0 max</sub>	slope resistance *	4.1		mΩ



#### Outlines SOT-227B (minibloc)



Dim.	Millir	meter	Inches			
DIM.	min max		min	max		
Α	31.50	31.88	1.240	1.255		
В	7.80	8.20	0.307	0.323		
С	4.09	4.29	0.161	0.169		
D	4.09	4.29	0.161	0.169		
Е	4.09	4.29	0.161	0.169		
F	14.91	15.11	0.587	0.595		
G	30.12	30.30	1.186	1.193		
Н	37.80	38.23	1.488	1.505		
J	11.68	12.22	0.460	0.481		
K	8.92	9.60	0.351	0.378		
L	0.74	0.84	0.029	0.033		
M	12.50	13.10	0.492	0.516		
N	25.15	25.42	0.990	1.001		
0	1.95	2.13	0.077	0.084		
Р	4.95	6.20	0.195	0.244		
Q	26.54	26.90	1.045	1.059		
R	3.94	4.42	0.155	0.167		
S	4.55	4.85	0.179	0.191		
Т	24.59	25.25	0.968	0.994		
U	-0.05	0.10	-0.002	0.004		
V	3.20	5.50	0.126	0.217		
W	19.81	21.08	0.780	0.830		
Z	2.50	2.70	0.098	0.106		





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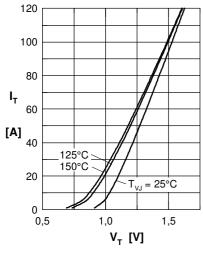


Fig. 1 Forward characteristics

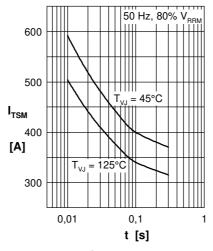


Fig. 2 Surge overload current

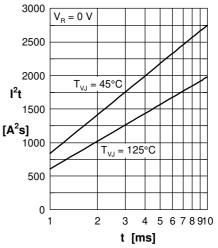


Fig. 3 I<sup>2</sup>t versus time (1-10 ms)

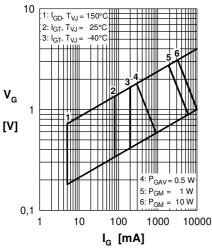


Fig. 4 Gate trigger characteristics

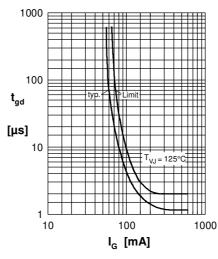


Fig. 5 Gate controlled delay time

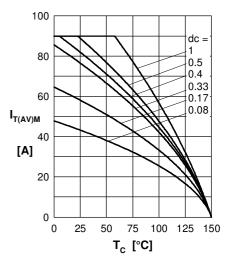


Fig. 6 Max. forward current at case temperature

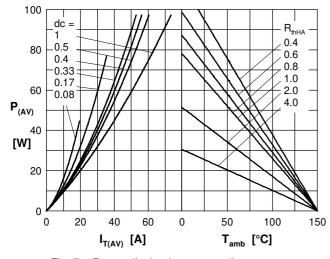


Fig. 7a Power dissipation versus direct output current Fig. 7b and ambient temperature

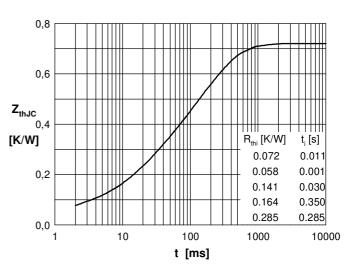


Fig. 8 Transient thermal impedance junction to case

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25.163.2453.0 25.3	163.4253.0	25.190.2053.0	25.194.3453.0	25.320.4853.1	25.320.5253.1	25.326.3253.1	25.326.3553.1	25.330.1653.1
25.330.4753.1 25.3	330.5253.1	25.334.3253.1	25.334.3353.1	25.350.2053.0	25.352.4753.1	25.522.3253.0	<u>T483C</u> <u>T484C</u>	<u>T485F</u> <u>T485H</u>
T512F-YEB T513	F T514F T	554 <u>T612FSE</u>	25.161.3453.0	25.179.2253.0	25.194.3253.0	25.325.1253.1	25.326.4253.1	25.330.0953.1
25.332.4353.1 25.3	350.1653.0	25.350.2453.0	25.352.1453.0	25.352.1653.0	25.352.2453.0	25.352.5453.1	25.522.3353.0	25.602.4053.0
25.640.5053.0								